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PRODUCT CHANGE NOTIFICATION

PCN: PCN184902

Date: December 10, 2018

Subject: Qualification of Fab 25 as an Additional Wafer Fab Site, EME-G660B Mold Compound and Marketing Part Number Change for Select Automotive MCU Products

To: GENERAL INBOX
PREMIER FARNELL
ProductChangeNotices@premierfarnell.com

Change Type: Major

Description of Change:

Cypress announces the qualification of Fab 25 (5204 East Ben White Boulevard, Austin, TX 78741, USA) as an additional wafer fab site for select automotive MCU products. The current products are fabricated at ON Semiconductor Aizu Co., Ltd, which was former Aizu Fujitsu Semiconductor Manufacturing Limited (AFSM) Japan. Cypress also announces that the package mold material is changing to the standard J-Devices EME-G660B mold compound. In addition, the part number is changing from an MB prefix to a CY prefix, including a marking change of "F-logo" or "Spansion logo" removal. These changes correspond to Group 2 (GR2-C) in APCN173705C.

Changes	Current	New
Wafer Fab Site	ON Semiconductor Aizu Co., Ltd, Japan	Fab 25, USA
Mold Compound	Hitachi Epoxy CEL-9210H	Sumitomo Epoxy EME-G660B
Part Number	MB***	CY***
Logo Marking	F-logo or Spansion logo	No logo

Benefit of Change:

Qualification of alternate manufacturing sites is part of the ongoing flexible manufacturing initiative announced by Cypress. The goal of the flexible manufacturing initiative is to provide the means for Cypress to continue to meet delivery commitments through dynamic, changing market conditions.

Part Numbers Affected: 163

See the attached 'Affected Parts List' file for a list of all part numbers affected by this change. Note that any new parts that are introduced after the publication of this PCN will include all changes outlined in this PCN.



Qualification Status:

This wafer fab site has been qualified through a series of tests documented in Qualification Test Plans QTP#172504 and QTP#173908. These qualification reports can be found as attachments to this PCN or by visiting www.cypress.com and typing the QTP number in the keyword search window.

Sample Status:

Qualification samples may not be built ahead of time for all part numbers affected by this change. Please review the attached 'Affected Parts List' file for a list of affected part numbers with their associated Fab 25 sample ordering part numbers. Samples are available now unless there is an indication that the sample ordering part numbers are subject to lead times. If you require qualification samples, please contact your local Cypress sales representative as soon as possible, preferably within 30 days of the date of this PCN, to place any sample orders.

Approximate Implementation Date:

Effective 90 days from the date of this notification or upon customer approval, whichever comes first, all shipments of Commercial, Industrial and Automotive non-PPAP part numbers in the attached file will be supplied from Fab 25 or other approved wafer fabrication sites.

For Automotive PPAP part numbers this change will be effective upon customer approval.

Anticipated Impact:

Products fabricated at the new site are completely compatible with existing products from form, fit, functional, parametric and quality performance perspectives.

Cypress also recommends that customers take this opportunity to review these changes against current application notes, system design considerations and customer environment conditions to assess impact (if any) to their application.

Method of Identification:

Cypress maintains traceability of product to wafer level, including wafer fabrication location, through the lot number marked on the package.

Response Required:

No response is required.

For additional information regarding this change, contact your local sales representative or contact the PCN Administrator at pcn_adm@cypress.com.

Sincerely,

Cypress PCN Administration